

In the Abstract:

Please replace the Abstract with the following amended Abstract:

~~The invention relates to a cooling structure of an electronic equipment needing forced air cooling by fans and so force and has an object to enhance a cooling capacity and enhance a mounting efficiency of the substrate units. The~~ A ~~cooling structure of an electronic equipment needing forced air cooling comprises, to achieve the above object, includes~~ substrate housing parts, an upstream side duct, a downstream side duct, an ~~exhaust device means and an air adjusting means part.~~ The substrate housing parts detachably house therein one or plurality of substrate units, and the downstream side duct allows the cooling ~~air for cooling,~~ which passed from the upstream side duct through the substrate housing part, to flow. The ~~exhaust means~~ device ~~is provided at the~~ an ~~exhaust part to forcibly discharge air to the outside air, thereby allowing the~~ cooling air for cooling ~~to flow to the substrate housing parts, and the~~ The ~~air adjusting means part adjusts the~~ volume for cooling ~~air for cooling~~ which flows to the downstream side duct.